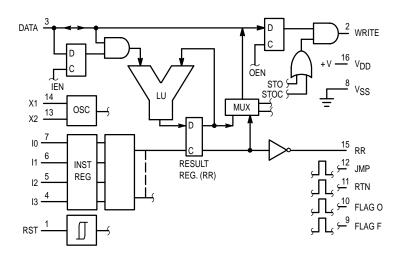
# **Industrial Control Unit**

The MC14500B Industrial Control Unit (ICU) is a single—bit CMOS processor. The ICU is designed for use in systems requiring decisions based on successive single—bit information. An external ROM stores the control program. With a program counter (and output latches and input multiplexers, if required) the ICU in a system forms a stored—program controller that replaces combinatorial logic. Applications include relay logic processing, serial data manipulation and control. The ICU also may control an MPU or be controlled by an MPU.

- 16 Instructions
- DC to 1.0 MHz Operation at VDD = 5 V
- On-Chip Clock (Oscillator)
- Executes One Instruction per Clock Cycle
- 3 to 18 V Operation
- Low Quiescent Current Characteristic of CMOS Devices
- Capable of Driving One Low–Power Schottky Load or Two Low–Power TTL Loads over Full Temperature Range

## **BLOCK DIAGRAM**



X1 — OSCILLATOR OUTPUT X2 — OSCILLATOR INPUT

# MC14500B



L SUFFIX CERAMIC CASE 620



P SUFFIX PLASTIC CASE 648

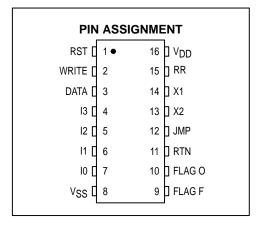


DW SUFFIX SOIC CASE 751G

## **ORDERING INFORMATION**

MC14XXXBCP Plastic MC14XXXBCL Ceramic MC14XXXBDW SOIC

 $T_A = -55^{\circ}$  to 125°C for all packages.



# MAXIMUM RATINGS\* (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage	- 0.5 to + 18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage (DC or Transient)	– 0.5 to V <sub>DD</sub> + 0.5	V
l <sub>in</sub> , lout	Input or Output Current (DC or Transient), per Pin	± 10	mA
PD	Power Dissipation, per Package†	500	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature (8-Second Soldering)	260	°C

<sup>\*</sup> Maximum Ratings are those values beyond which damage to the device may occur. †Temperature Derating:

Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C Ceramic "L" Packages: – 12 mW/°C From 100°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$ 

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V<sub>SS</sub> or V<sub>DD</sub>). Unused outputs must be left open.

# **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

			V <sub>DD</sub>	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Тур#	Max	Min	Max	Unit
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level	VOL	5.0 10 15	_ _ _	0.05 0.05 0.05		0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level	VOH	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95		Vdc
Input Voltage RST, D, X2 (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)		VIL	5.0 10 15	_ _ _	1.5 3.0 4.0	_ _ _	2.25 4.50 6.75	1.5 3.0 4.0		1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	VIH	5.0 10 15	3.5 7.0 11	  -  -  -	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	_ _ _	Vdc
Input Voltage # I0, I1, I2, I3 (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level	VIL	5.0 10 15	_ _ _	0.8 1.6 2.4	_ _ _	1.1 2.2 3.4	0.8 1.6 2.4		0.8 1.6 2.4	Vdc
(V <sub>O</sub> = 0.5 or 4.5 Vdc) (V <sub>O</sub> = 1.0 or 9.0 Vdc) (V <sub>O</sub> = 1.5 or 13.5 Vdc)	"1" Level	VIH	5.0 10 15	2.0 6.0 10	_ _ _	2.0 6.0 10	1.9 3.1 4.3	_ _ _	2.0 6.0 10	_ _ _	Vdc
Output Drive Current Data, Write (VOH = 4.6 Vdc) (VOH = 9.5 Vdc) (VOH = 13.5 Vdc)	Source	lOH	5.0 10 15	- 1.2 - 3.6 - 7.2	_ _ _	- 1.0 - 3.0 - 6.0	- 2.0 - 6.0 - 12	_ _ _	- 0.7 - 2.1 - 4.2	  -  -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	lOL	5.0 10 15	1.9 3.6 7.2	_ _ _	1.6 3.0 6.0	3.2 6.0 12	_ _ _	1.1 2.1 4.2	_ _ _	mAdc
Output Drive Current Other Outputs  (VOH = 2.5 Vdc)  (VOH = 4.6 Vdc)  (VOH = 9.5 Vdc)  (VOH = 13.5 Vdc)	Source	ЮН	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	_ _ _ _	- 1.7 - 0.36 - 0.9 - 2.4	  -  -  -	mAdc
(V <sub>OL</sub> = 0.4 Vdc) (V <sub>OL</sub> = 0.5 Vdc) (V <sub>OL</sub> = 1.5 Vdc)	Sink	lOL	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4		mAdc

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

**ELECTRICAL CHARACTERISTICS** — **continued** (Voltages Referenced to V<sub>SS</sub>)

		V <sub>DD</sub>	-55	5°C		25°C		125	5°C	
Characteristic	Symbol	Vdc	Min	Max	Min	Тур#	Max	Min	Max	Unit
Input Current, RST	l <sub>in</sub>	15	25	_	_	150	_	_	250	μAdc
Input Current	l <sub>in</sub>	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (Data)	C <sub>in</sub>	_	_	_	_	15	_	_	_	pF
Input Capacitance (All Other Inputs)	C <sub>in</sub>	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package) $I_{out} = 0 \mu A$ , $V_{in} = 0 \text{ or } V_{DD}$	I <sub>DD</sub>	5.0 10 15		5.0 10 20	1 1 1	0.005 0.010 0.015	5.0 10 20	_ 	150 300 600	μAdc
**Total Supply Current at an External Load Capacitance (C <sub>L</sub> ) on All Outputs	lΤ		$I_{T} = (1.5 \mu\text{A/kHz})  f + I_{DD}$ $I_{T} = (3.0 \mu\text{A/kHz})  f + I_{DD}$ $I_{T} = (4.5 \mu\text{A/kHz})  f + I_{DD}$			μAdc				

<sup>\*\*</sup>The formulas given are for the typical characteristics only at 25°C.

**SWITCHING CHARACTERISTICS\*** ( $T_A = 25^{\circ}C$ ;  $t_r = t_f = 20$  ns for X and I inputs;  $C_L = 50$  pF for JMP, X1, RR, Flag O, Flag F;  $C_L = 130$  pF + 1 TTL load for Data and Write.)

		V <sub>DD</sub>	All Types			
Characteristic	Symbol	Vdc	Min	Typ #	Max	Unit
Propagation Delay Time, X1 to RR	<sup>t</sup> PLH <sup>,</sup> <sup>t</sup> PHL	5.0 10 15	_ _ _	250 125 100	500 250 200	ns
X1 to Flag F, Flag O, RTN, JMP		5.0 10 15	=	200 100 85	400 200 170	
X1 to Write		5.0 10 15	_ _ _	225 125 100	450 250 200	
X1 to Data		5.0 10 15	_ _ _	250 120 100	500 240 200	
RST to RR		5.0 10 15		250 125 100	500 250 200	
RST to X1		5.0 10 15	_ _ _	450 200 150	Note 1	
RST to Flag F, Flag O, RTN, JMP		5.0 10 15		400 200 150	800 400 300	
RST to Write, Data		5.0 10 15		450 225 175	900 450 350	
Clock Pulse Width, X1	<sup>t</sup> W(cl)	5.0 10 15	400 200 180	200 100 90	=	ns
Rent Pulse Width, RST	<sup>t</sup> W(R)	5.0 10 15	500 250 200	250 125 100		ns
Setup Time — Instruction	t <sub>su(I)</sub>	5.0 10 15	400 250 180	200 125 90	_	ns
Data	t <sub>su(D)</sub>	5.0 10 15	200 100 80	100 50 40	_ _ _	
Hold Time — Instruction	t <sub>h(I)</sub>	5.0 10 15	100 50 50	0 0 0	_ _ _	ns
Data	<sup>t</sup> h(D)	5.0 10 15	200 100 100	100 50 50	_ _ _	

NOTE 1. Maximum Reset Delay may extend to one-half clock period.

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

<sup>#</sup>Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

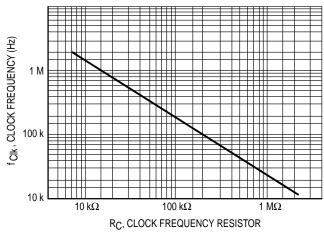


Figure 1. Typical Clock Frequency
versus Resistor (Rc)

Pin No.	Function	Symbols
1	Chip Reset	RST
2	Write Pulse	Write
3	Data In/Out	Data
4	MSB Instruction Word	l <sub>3</sub>
5	Bit 2 Instruction Word	l <sub>2</sub>
6	Bit 1 Instruction Word	I <sub>1</sub>
7	LSB Instruction Word	l <sub>0</sub>
8	Negative Supply (Ground)	Vss
9	Flag on NOP F	Flag F
10	Flag on NOP O	Flag O
11	Subroutine Return Flag	RTN
12	Jump Instruction Flag	JMP
13	Oscillator Input	X2
14	Oscillator Output	X1
15	Result Register	RR
16	Positive Supply	$V_{DD}$

Table 1. MC14500B Instruction Set

Instruct	Instruction Code Mner		Action
0	0000	NOPO	No change in registers. RR → RR, Flag O → ¬¬¬¬
1	0001	LD	Load result register. Data → RR
2	0010	LDC	Load complement. Data → RR
3	0011	AND	Logical AND. RR • Data → RR
4	0100	ANDC	Logical AND complement. RR • Data → RR
5	0101	OR	Logical OR. RR + Data → RR
6	0110	ORC	Logical OR complement. RR + Data → RR
7	0111	XNOR	Exclusive NOR. If RR = Data, RR → 1
8	1000	STO	Store. RR → Data Pin, Write → \( \square\)
9	1001	STOC	Store complement. RR → Data Pin, Write → □
Α	1010	IEN	Input enable. Data → IEN Register
В	1011	OEN	Output enable. Data → OEN Register
С	1100	JMP	Jump. JMP Flag →  □
D	1101	RTN	Return. RTN Flag →
E	1110	SKZ	Skip next instruction if RR = 0
F	1111	NOPF	No change in registers. RR $\rightarrow$ RR, Flag F $\rightarrow$ $\square$

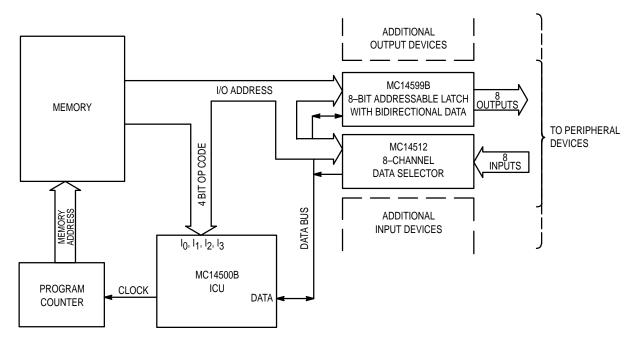
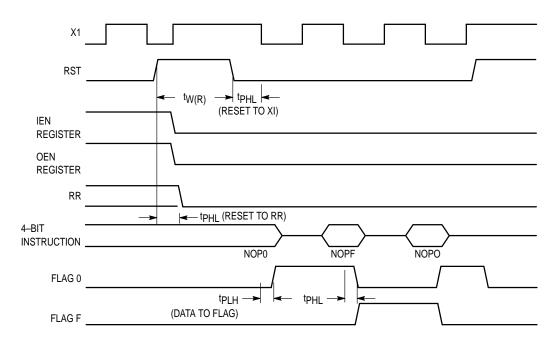


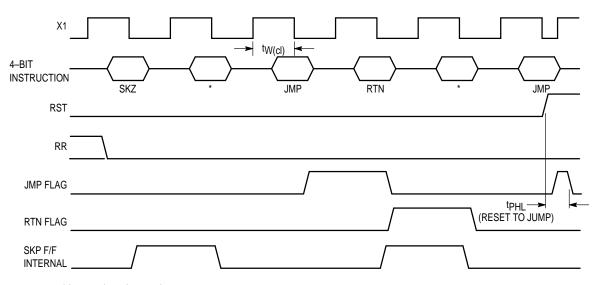
Figure 2. Outline of a Typical Organization for a MC14500B-Based System

# **TIMING WAVEFORMS**

# Instructions NOPO, NOPF RR, IEN, OEN remain unaffected



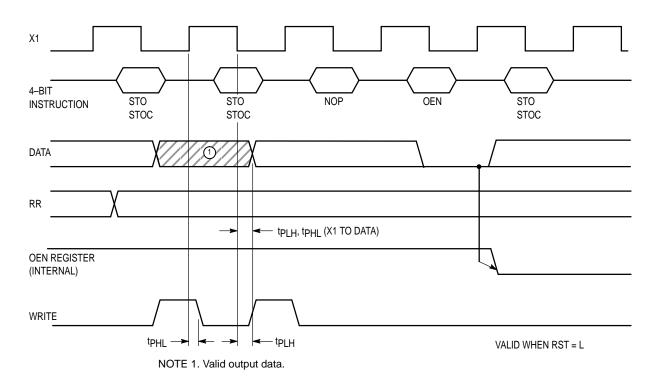
# Instructions SKZ, JMP, RTN RR, IEN, OEN remain unaffected



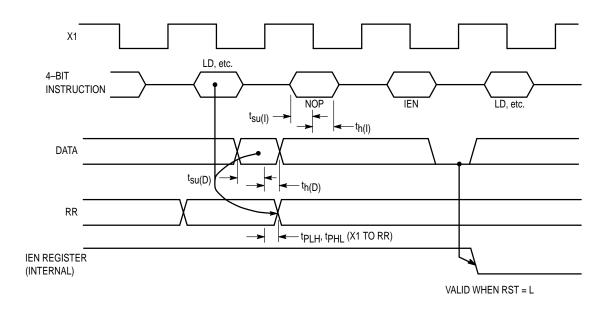
<sup>\*</sup> Instructions Ignored.

# **TIMING WAVEFORMS**

# Instructions STO, STOC, OEN

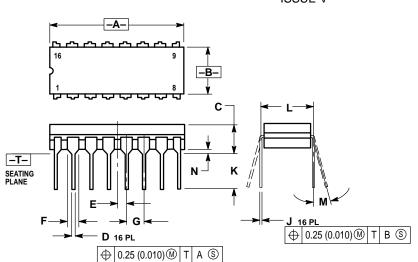


# Instructions LD, LDC, AND, ANDC OR, ORC, XNOR, IEN



# **OUTLINE DIMENSIONS**

# **L SUFFIX** CERAMIC DIP PACKAGE CASE 620-10 ISSUE V



#### NOTES:

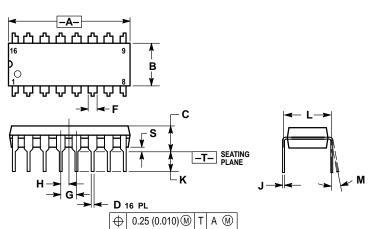
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: INCH.
  DIMENSION L TO CENTER OF LEAD WHEN
  FORMED PARALLEL.
  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
М	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

# **P SUFFIX**

PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



## NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

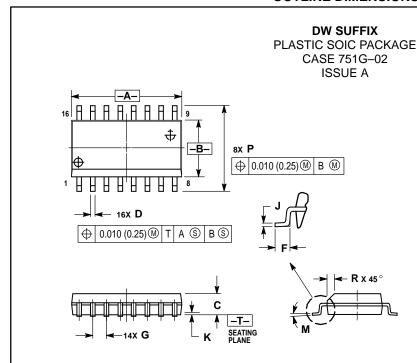
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MIN MAX		MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

## **OUTLINE DIMENSIONS**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	10.15	10.45	0.400	0.411	
В	7.40	7.60	0.292	0.299	
С	2.35	2.65	0.093	0.104	
D	0.35	0.49	0.014	0.019	
F	0.50	0.90	0.020	0.035	
G	1.27	BSC	0.050 BSC		
J	0.25	0.32	0.010	0.012	
K	0.10	0.25	0.004	0.009	
M	0 °	7 °	0 °	7 °	
Р	10.05	10.55	0.395	0.415	
R	0.25	0.75	0.010	0.029	

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